	SPECIFI	CATION		
无	致電子股	份有限公	公司	
	桃園縣中壢市	5東園路13號		
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	TEL: +886-3- FAX: +886-3-			
SPEC. NO.: PS-308	339-XXXXX-XXX	REV	VISION: A	
PRODUCT NAME:	RJ45 IMC 10/100	/1000 Base-T C	ONNECTOR	
PRODUCT NO:	30839 SERIES			
PREPARED:	CHECKED:		APPROVED:	
DENG JIAN XIA		CHANG HO	KUO JUNG HSUN	1
DATE: 2020/06/16	DATE: 202	0/06/16	DATE: 2020/06/16	



TITLE: RJ45 IMC 10/100/1000 Base-T CONNECTOR

RELEASE DATE: 2020.06.16

REVISION: A

ECN No: ECN-2006478

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1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
Α	ECN-2006478	NEW SPEC	DENGJIANXIANG	2020.06.16

ſ		s	Ace	es P/N: <mark>3(</mark>	839 series		
			0/1000 Base-T C	ONNEC	TOR		
	RELEASE DATE	: 2020.06.16	REVISION: A		ECN No: ECN-20064	78	PAGE: 4 OF8
1	SCOPE						
			performance, tests Base-T Connector.		lity requirements fo	DF	
	B APPLIC	ABLE DOCU	IMENTS				
	EIA-364:	ELECTRONICS	INDUSTRIES AS	SOCIATI	NC		
4	REQUI	REMENTS					
	4.1 Desig	n and Construct	tion				
	4.1.1			ruction ar	nd physical dimensi	ons specifie	d on applicable
	4.1.2	product drawin All materials co	•	nd the sta	ndard depends on	TQ-WI-1401	101.
	4.2 Mate	rials and Finish					
	4.2.1	Finish: (a) C (b) U	Performance Copp contact Area: Refer Inder-plating: Refe older Area: Refer t	r to the in er to the in	dividual drawings.		
	4.2.2	-	noplastic or Therm r to the individual c	-	High Temp., UL94∖	/-0	
	4.2.3		Steel or Copper A lating: Refer to the		al drawings.		
	4.3 Ratin	gs					
	4.3.1 4.3.2 4.3.3	Operating Tem	[AC(RMS.)/DC] M/ perature: Refer to erature: -40°C to +8	the indivi	dual drawings.		



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5 PERFORMANCE

5.1. Test Requirements and Procedures Summary

ltem	Requirement	Standard						
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.						
ELECTRICAL								
ltem	Requirement	Standard						
Low Level Contact Resistance	30mΩMax. (initial) 50mΩMax. (after test)	Mate connectors, measure by dry circuit, 20mV Max., 100mAMax. (EIA-364-23)						
Insulation Resistance	500 MΩ Min.	Un-mate connectors, apply 500 VDC between adjacent terminals and between terminals to ground. (EIA-364-21)						
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA Max.	Un-mate connectors, apply1500 VAC at sea level for 1 minute between input to output terminals. (EIA-364-20)						

	MECHANICA				
ltem	Requirement	Standard			
Durability (Locking device inoperative)	750 cycles Contact Resistance: 30mΩ Max. (initial) 50mΩ Max. (after test)	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09) Operation Speed : 25.4±3 mm per minute. Measure the force required to mate/un-mate connector. (EIA-364-13)			
Mating / Un-mating Forces (test with RJ45 plug latch depressed)	Mating Force: 22N Max. Un-mating Force: 44N Max.				
	ENVIRONMENT	AL			
Item	Requirement	Standard			
Resistance to Wave Soldering Heat	No damage or deformation. Contact Resistance: $30m\Omega$ Max. (initial) $50m\Omega$ Max. (after test)	Pre Heat:~130°C at 5°C/s Max. Peak Temp.:260°C Max, 10sec Max. (EIA-364-56)			

connectors
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Thermal Shock	See Product Qualification and Test Sequence Group 2	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32,Test condition I)
Humidity	See Product Qualification and Test Sequence Group 2	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature Life	See Product Qualification and Test Sequence Group 3	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)
Cold Resistance	See Product Qualification and Test Sequence Group 4	Subject mated connectors to temperature life at -40°C for 96 hours. (EIA-364-59)
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
Salt Spray	No damage. Contact Resistance: 30mΩ Max. (initial) 50mΩ Max. (after test)	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C for 24 hours (EIA-364-26)
Solderability	Solderable area shall have minimum of 95% solder coverage.	Immerse terminal tail into solder bath, and temperature at 245±5°C, for 3~5 sec. (EIA-364-52)

		Aces P/N: 30839 series
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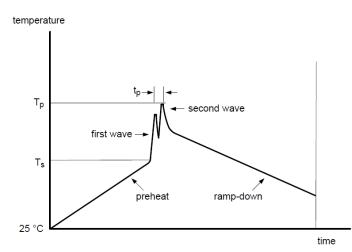
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6 RECOMMENDED SOLDERING CONDITION

Wave Soldering Process:

Profile Feature	SnPb eutectic assembly	Pb-free assembly		
Average ramp-up rate	~ 200 °C/s	~ 200 °C/s		
Heating rate during preheat	typical 1-2, max 4 °C/s	typical 1-2, max 4 °C/s		
Final preheat temperature T_{S}	~ 130 °C	~ 130 °C		
Peak temperature T _P	235 °C	260 °C		
Time within peak temperature $t_{\mbox{\tiny P}}$	10 s	10 s		
Ramp-down rate	5 °C/s maximum	5 °C/s maximum		

Wave Soldering Profile





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7 PRODUCT QUALIFICATION AND TEST SEQUENCE

					Test C	Group				
Test or Examination	1	2	3	4	5	6	7	8		
	Test Sequence									
Examination of Product	1、6	1、6	1、5	1、5	1、4	1、4	1、3	1、4		
Low Level Contact Resistance	2、7				2、5	2、5		2 \ 5		
Insulation Resistance		2、7	2、6	2、6						
Dielectric Withstanding Voltage		3、8	3 • 7	3、7						
Mating / Un-mating Forces	3、5									
Durability (Locking device inoperative)	4									
Thermal Shock		4								
Humidity		5								
Temperature Life			4							
Cold Resistance				4						
Vibration					3					
Salt Spray						3				
Solderability							2			
Resistance to Wave Soldering Heat								3		
Sample Size	4	4	4	4	4	4	2	4		